2SK2573 (Tentative)

Silicon N-Channel Power F-MOS FET

Features

- Avalanche energy capacity guaranteed
- High-speed switching
- Low ON-resistance
- No secondary breakdown

Applications

- Contactless relay
- Diving circuit for a solenoid
- Driving circuit for a motor
- Control equipment
- Switching power supply

Absolute Maximum Ratings ($T_C = 25^{\circ}C$)

Parameter		Symbol	Ratings	Unit	
Drain to Source breakdown voltage		V _{DSS}	500	V	
Gate to Source voltage		V _{GSS}	±30	V	
Drain current	DC	I _D ±20		А	
	Pulse	I _{DP} ±40		А	
Avalanche energy capacity		EAS*	20	mJ	
Allowable power	$T_C = 25^{\circ}C$	D	100	W	
dissipation	$Ta = 25^{\circ}C$	PD	3		
Channel temperature		T _{ch}	150	°C	
Storage temperature		T _{stg}	-55 to +150	°C	



* $L = 0.1 \text{mH}, I_L = 20 \text{A}, 1 \text{ pulse}$

Electrical Characteristics ($T_C = 25^{\circ}C$)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I _{DSS}	$V_{DS}=400V,V_{GS}=0$			100	μA
Gate to Source leakage current	I _{GSS}	$V_{GS}=\pm 20V,V_{DS}=0$			±1	μΑ
Drain to Source breakdown voltage	V _{DSS}	$I_D = 1 \text{mA}, V_{GS} = 0$	500			V
Gate threshold voltage	V _{th}	$V_{DS} = 25V, I_D = 1mA$	1		5	V
Drain to Source ON-resistance	R _{DS(on)}	$V_{GS} = 10V, I_D = 10A$		0.32	0.4	Ω
Forward transfer admittance	Y _{fs}	$V_{DS} = 25V, I_D = 10A$	7.2	12		S
Diode forward voltage	V _{DSF}	$I_{DR} = 20A, V_{GS} = 0$			-2.8	V
Input capacitance (Common Source)	C _{iss}	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$		3000		pF
Output capacitance (Common Source)	C _{oss}			430		pF
Reverse transfer capacitance (Common Source)	C _{rss}			175		pF
Turn-on time	t _{on}	$V_{DD} = 150V, I_D = 10A$ $V_{GS} = 10V, R_L = 15\Omega$		150		ns
Fall time	t _f			140		ns
Turn-off time (delay time)	t _{d(off)}			480		ns
Thermal resistance between channel and case	R _{th(ch-c)}				1.25	°C/W
Thermal resistance between channel and atmosphere	R _{th(ch-a)}				41.67	°C/W





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